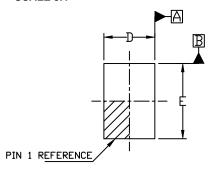
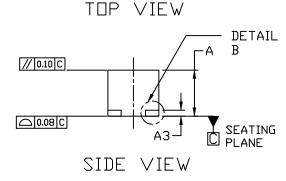


DATE 29 APR 2018

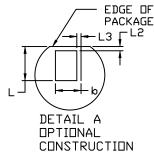






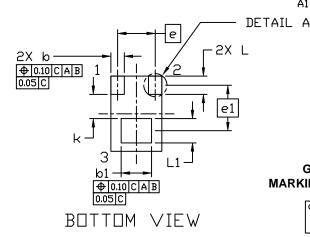
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 AND 61 APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 0.20 AND 0.25 FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE PLATED TERMINALS.



CHISTROCTION	
Γ ^{A3}	EXPOSED COPPER
	MOLDING COMPOUND
DETAIL B	CONSTRUCTION

	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.33	0.38	0.43
A1			0.07
АЗ	0.13 REF		
b	0.05	0.11	0.17
b1	0.20	0.25	0.30
D	0.32	0.42	0.52
Ε	0.52	0.62	0.72
e	0.30 BSC		
e1	0.38 BSC		
L	0.09	0.15	0.21
L1	0.15	0.20	0.25
L2			0.03
L3			0.03
k	().20 REF	



GENERIC MARKING DIAGRAM*



= Specific Device Code = Date Code

PACKAGE DUTLINE		− 0.35
0.29		0.30
0.11		2X 0.25
2X 0.21 0.52	 	0.31 PITCH
RECON	MEN]	DED

MOUNTING FOOTPRINT

40400	Electronic versions are uncontrolled except when accessed directly from the Document Repository.
marking. Pb-Fr	sheet for actual part ee indicator, "G", may nt. Some products may eneric Marking.

DOCUMENT NUMBER: 98AON64946G Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. **DESCRIPTION:** XDFN3 0.42x0.62, 0.3P PAGE 1 OF 1

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^{*}This information is generic. Please refer